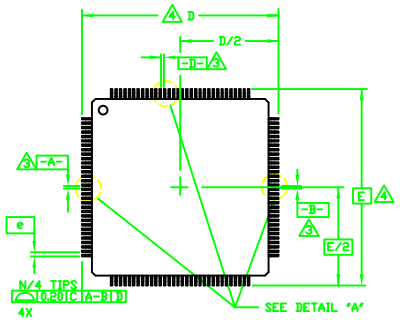
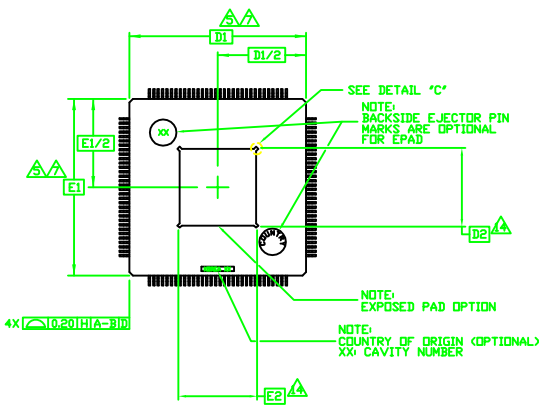
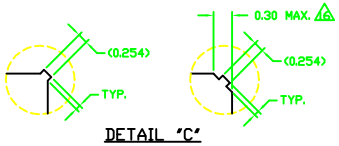
REVISION HISTORY				
REV	DESCRIPTION	DATE	ENGINEER	RELEASED
00	INITIAL RELEASE PER DCN #A34739.	02/27/1992	YMK	XXX
01	INCORPORATED PER DCN #D20037.	07/14/1992	YMK	XXX
02	INCORPORATED PER DCN #A35403.	08/28/1992	YMK	XXX
03	INCORPORATED PER DCN #A35776.	09/10/1992	YMK	XXX
04	INCORPORATED PER DCN #D20857.	09/15/1992	YMK	XXX
05	INCORPORATED PER DNC #D21029.	10/21/1992	YMK	XXX
06	REVISED PER DCN #D21568.	09/23/1994	YMK	XXX
07	REVISED PER DCN #D21715.	03/08/1995	YMK	XXX
08	REVISED PER DCN #D22150.	03/08/1995	YMK	XXX
09	REVISED PER DCN #D24552.	08/24/1998	MP	XXX
10	INCORPORATED PER DCN #D26832.	07/06/2001	AAYRE	AAYRE

TOP VIEW



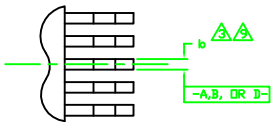
BOTTOM VIEW



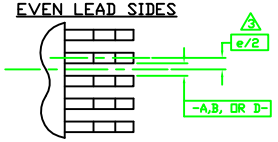


DETAIL 'C'
(EXPOSED PAD CORNER DETAIL)

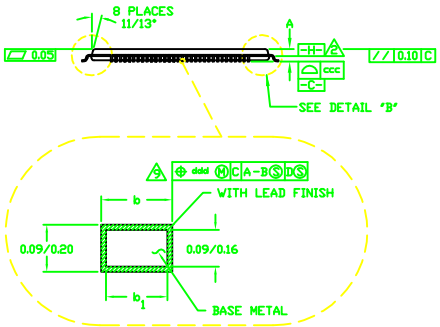
ODD LEAD SIDES

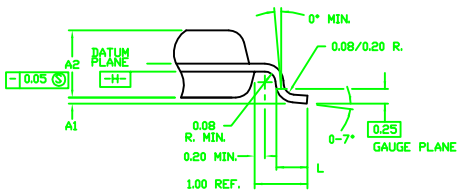


EVEN LEAD SIDES



DETAIL 'A'





DETAIL 'B'

XXXX	XXXX	XXXX	XXXX
DESCRIPTION	MATERIAL	PLATE	SID NUMBER

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL X.X ±0.1 mm; X.XX ±0.05 mm; X.XXX ±0.025 mm

ANGULAR ±1°

INTERPRET DIM AND TOL PER ASME Y14.5M – 1994

THIRD ANGLE PROJECTION

PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING

APPROVALS		DATE
DRAWN	CJ KIM	02/27/1992
CHECKED	YOON JH	02/27/1992
APPROVED	YW HEO	02/27/1992
RELEASED	YK KANG	02/27/1992

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE, MATRIX, TQFP,
12 X 12 mm BODY, 1.00/0.10 mm FORM,
1.00 mm THICK (OPTIONAL ePAD)

SIZE	DWG NUMBER	REV
A3	32774	10

SCALE	CONTROL CODE	SHEET
8:1	XXXX	1 OF 2

FORM NO. MDFORM3J.DWG